

LNPTM STAT-KONTM COMPOUND WE003ER

WC-1003 EM ER

DESCRIPTION

LNP STAT-KON WE003ER compound is based on Polybutylene Terephthalate (PBT) resin containing 15% carbon fiber. Added features of this grade include: Easy Molding, Easy Release, Electrically Conductive.

GENERAL INFORMATION

Features	Electrically Conductive, Good Processability, Enhanced mold release, Carbon fiber filled, High stiffness/Strength, No PFAS intentionally added
Fillers	Carbon Fiber
Polymer Types	Polybutylene Terephthalate (PBT)
Processing Techniques	Injection Molding

INDUSTRY

Electrical and Electronics
Industrial

SUB INDUSTRY

Electronic Components
Material Handling

TYPICAL PROPERTY VALUES

Revision 20230720

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, break, 5 mm/min	127	MPa	ISO 527
Tensile Strain, break, 5 mm/min	2.1	%	ISO 527
Tensile Modulus, 1 mm/min	10800	MPa	ISO 527
Flexural Stress, break, 2 mm/min	160	MPa	ISO 178
Flexural Modulus, 2 mm/min	8800	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched 80*10*4 +23°C	35	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	6	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
CTE, -40°C to 40°C, flow	2.5E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	7.5E-05	1/°C	ISO 11359-2
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	219	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	194	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Mold Shrinkage on Tensile Bar, flow ⁽²⁾	0.2 – 0.4	%	SABIC method
Density	1.35	g/cm ³	ISO 1183
ELECTRICAL ⁽¹⁾			
Surface Resistivity ⁽³⁾	1.E+02 – 1.E+04	Ω	ASTM D257
INJECTION MOLDING ⁽⁴⁾			
Drying Temperature	120	°C	
Drying Time	4	Hrs	

© 2023 Copyright by SABIC. All rights reserved

CHEMISTRY THAT MATTERS™

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Maximum Moisture Content	0.05	%	
Melt Temperature	240 – 265	°C	
Front - Zone 3 Temperature	260 – 270	°C	
Middle - Zone 2 Temperature	245 – 255	°C	
Rear - Zone 1 Temperature	220 – 230	°C	
Mold Temperature	80 – 100	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Measurement meets requirements as specified in ASTM D4496.
- (4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

MORE INFORMATION

For curve data and CAE cards, please visit and register at <https://materialfinder.sabic-specialties.com>

DISCLAIMER

Any sale by SABIC, its subsidiaries and affiliates (each a "seller"), is made exclusively under seller's standard conditions of sale (available upon request) unless agreed otherwise in writing and signed on behalf of the seller. While the information contained herein is given in good faith, SELLER MAKES NO WARRANTY, EXPRESS OR IMPLIED, INCLUDING MERCHANTABILITY AND NON-INFRINGEMENT OF INTELLECTUAL PROPERTY, NOR ASSUMES ANY LIABILITY, DIRECT OR INDIRECT, WITH RESPECT TO THE PERFORMANCE, SUITABILITY OR FITNESS FOR INTENDED USE OR PURPOSE OF THESE PRODUCTS IN ANY APPLICATION. Each customer must determine the suitability of seller materials for the customer's particular use through appropriate testing and analysis. No statement by seller concerning a possible use of any product, service or design is intended, or should be construed, to grant any license under any patent or other intellectual property right.